

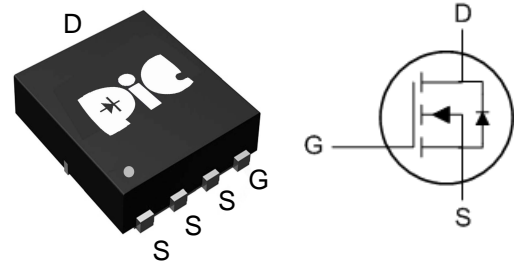
## ➤ General Description

This PAN40SY86Y N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent  $R_{ds(On)}$  performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

## ➤ Feature

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent  $CdV/dt$  effect decline
- Advanced high cell density Trench technology

## ➤ DFN5X6A-EP1



## ➤ Application

- DC/DC Primary Side Switch
- Industrial Synchronous
- Rectification Load Switch
- DC/DC Converters
- SMPS Synchronous Rectification

## ➤ Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, $V_{GS} @ 10V_{1,6}$	$I_D @ T_C=25^\circ C$	220	A
Continuous Drain Current, $V_{GS} @ 10V_{1,6}$	$I_D @ T_C=100^\circ C$	140	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	400	A
Single Pulse Avalanche Energy <sup>3</sup>	EAS	562	mJ
Avalanche Current	$I_{AS}$	106	A
Total Power Dissipation <sup>4</sup>	$P_D @ T_C=25^\circ C$	89	W
Storage Temperature Range	$T_{STG}$	-55 to 150	$^\circ C$
Operating Junction Temperature Range	$T_J$	-55 to 150	$^\circ C$
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	62	$^\circ C/W$
Thermal Resistance Junction-Case <sup>1</sup>	$R_{\theta JC}$	1.4	$^\circ C/W$

### ➤ Electrical Characteristics ( $T_J=25^\circ C$ Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	40	---	---	V
Static Drain-Source On-Resistance <sup>2</sup>	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	---	0.8	1.0	m $\Omega$
		$V_{GS}=4.5V, I_D=20A$	---	1.2	2.0	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.7	2.2	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=32V, V_{GS}=0V, T_J=25^\circ C$	---	---	1	uA
		$V_{DS}=32V, V_{GS}=0V, T_J=55^\circ C$	---	---	5	
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
Gate Resistance	$R_g$	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	1.3	---	$\Omega$
Total Gate Charge (10V)	$Q_g$	$V_{DS}=20V, V_{GS}=10V, I_D=20A$	---	126	---	nC
Total Gate Charge (4.5V)	$Q_g$		---	66	---	
Gate-Source Charge	$Q_{gs}$		---	17	---	
Gate-Drain Charge	$Q_{gd}$		---	28	---	
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=20V, V_{GS}=10V, R_G=1.5\Omega, I_D=20A$	---	15	---	ns
Rise Time	$T_r$		---	41	---	
Turn-Off Delay Time	$T_{d(off)}$		---	58	---	
Fall Time	$T_f$		---	30	---	
Input Capacitance	$C_{iss}$	$V_{DS}=20V, V_{GS}=0V, f=1MHz$	---	6780	---	pF
Output Capacitance	$C_{oss}$		---	2100	---	
Reverse Transfer Capacitance	$C_{rss}$		---	225	---	

### ➤ Diode Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current <sup>1,6</sup>	$I_s$	$V_G=V_D=0V, \text{Force Current}$	---	---	100	A
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	$V_{GS}=0V, I_s=1A, T_J=25^\circ C$	---	---	1.2	V

Note :

- 1 · Surface mounted on FR4 board using using 1 sq in pad size with 2OZ copper.
- 2 · Pulsed test : pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
- 3 · The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=106A$
- 4 · Ensure that the channel temperature does not exceed  $150^\circ C$ .
- 5 · The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.
- 6 · Package limitation current is 100A.

## ➤ Typical Characteristics

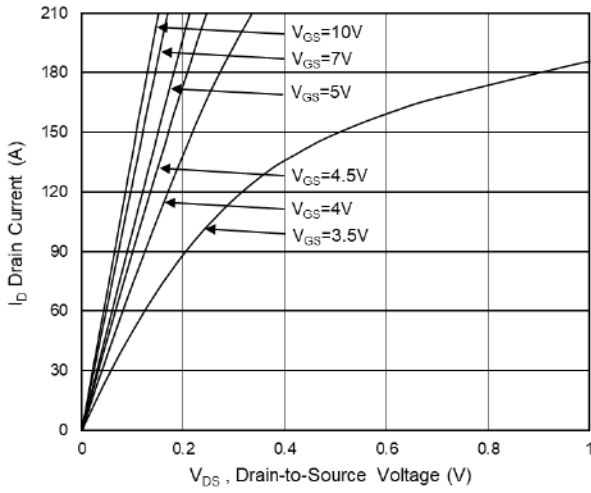


Fig.1 Typical Output Characteristics

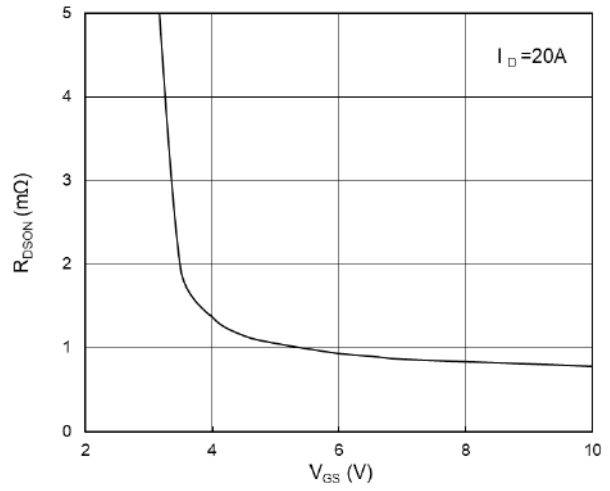


Fig.2 On-Resistance vs G-S Voltage

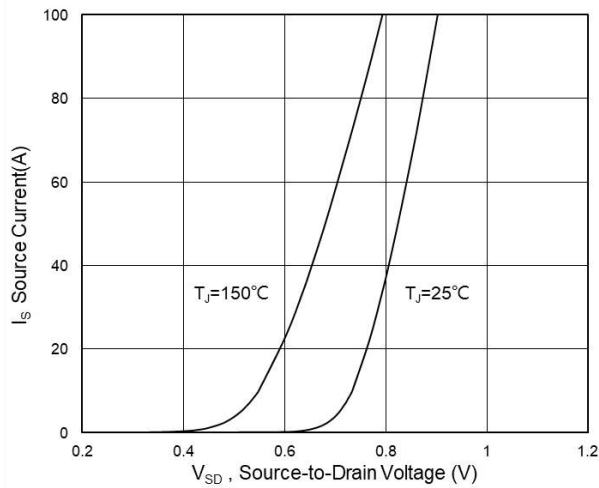


Fig.3 Source Drain Forward Characteristics

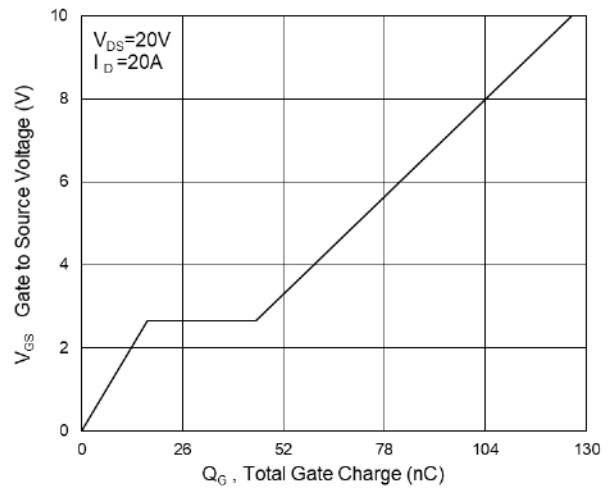


Fig.4 Gate-Charge Characteristics

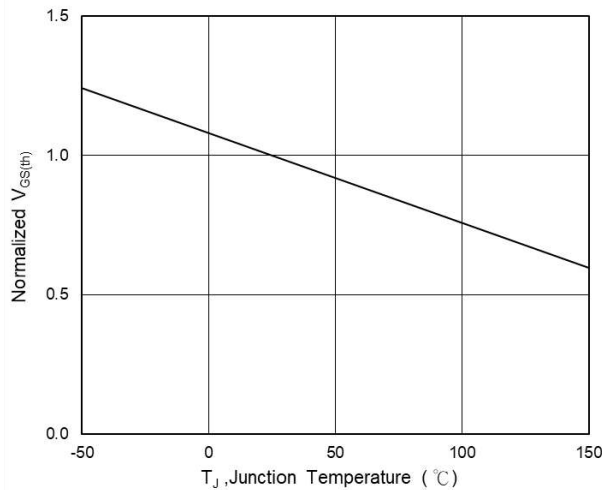


Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$

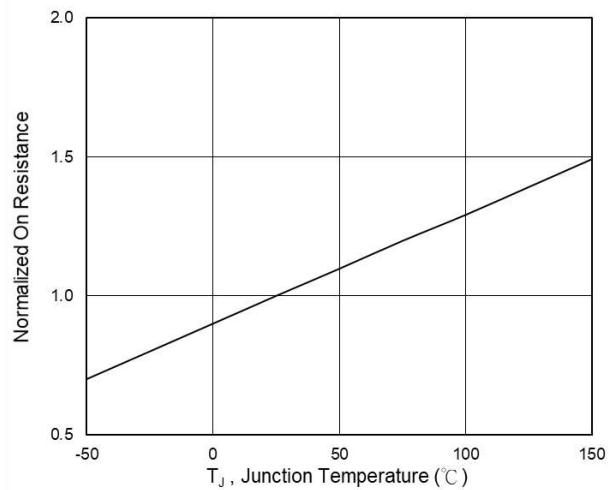
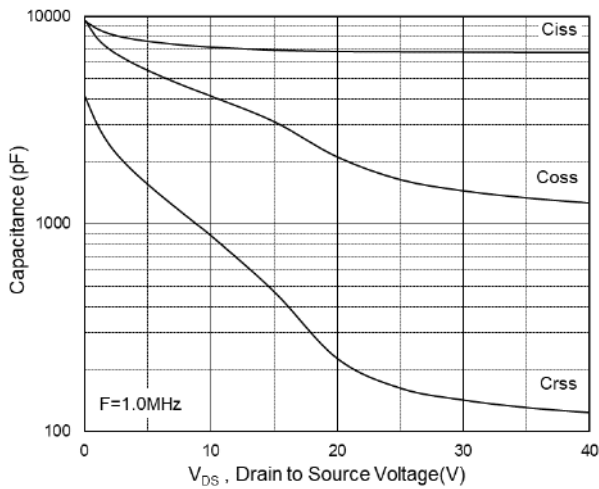
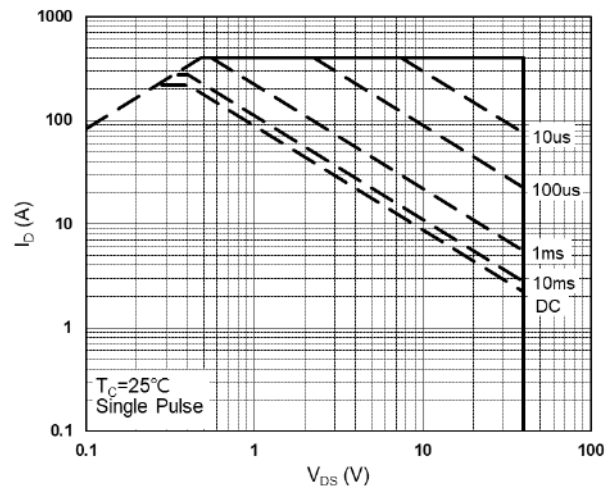


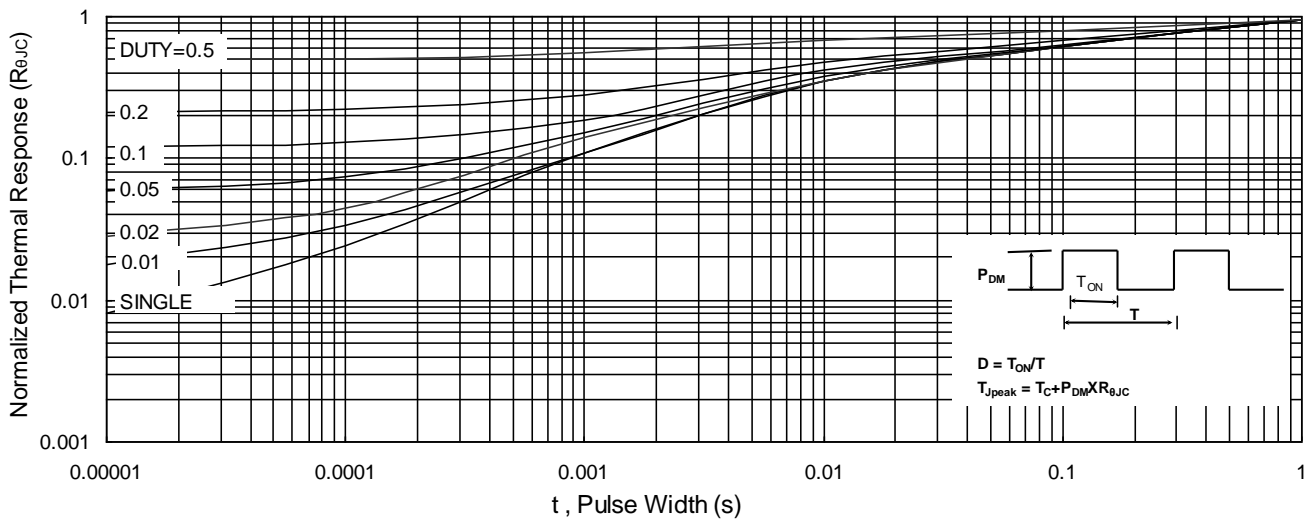
Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$



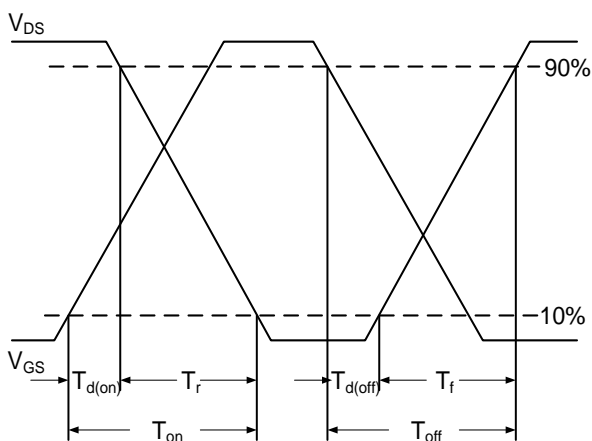
**Fig.7 Capacitance**



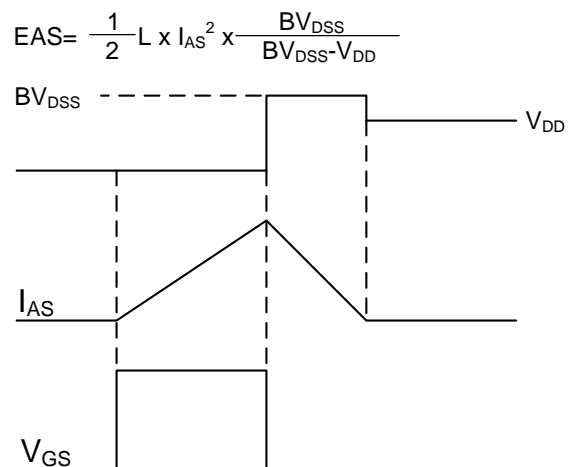
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

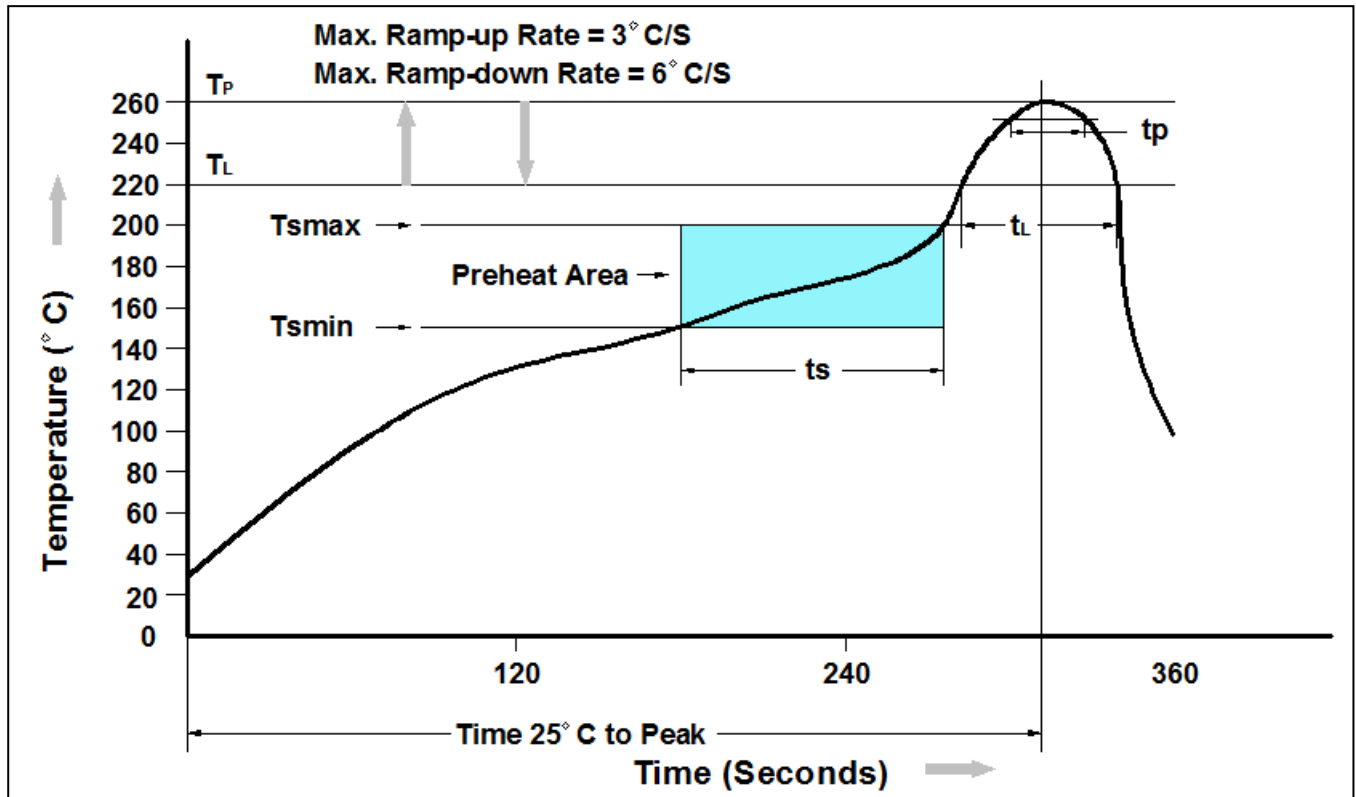


**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**

➤ Recommand IR Reflow Soldering Thermal Profile

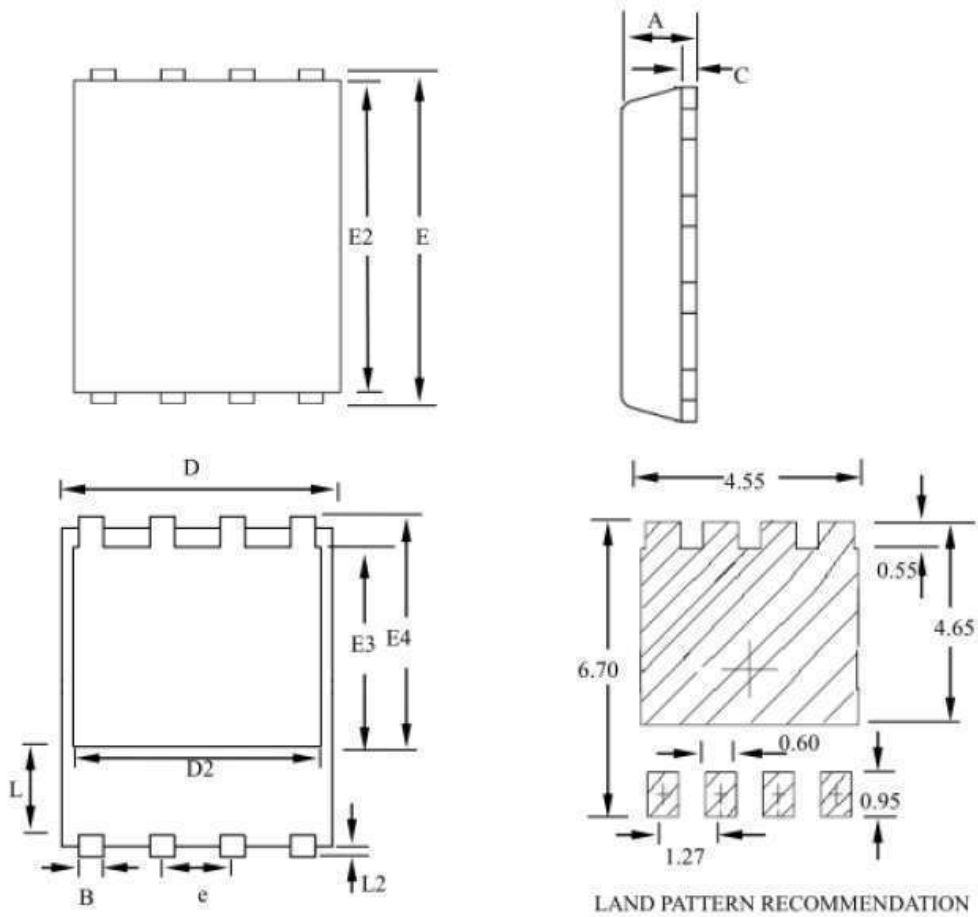


Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T <sub>smin</sub> )	150°C
Temperature Max. (T <sub>smax</sub> )	200°C
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds
Average Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

➤ Ordering Information

Part Number	Description	Quantity
PAN40SY86Y	DFN5X6A-EP1 Reel	3000 pcs

➤ Package Information ( DFN5X6A-EP1 )



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	--	1.20	0.031	--	0.047
B	0.30	--	0.51	0.012	--	0.020
C	0.15	--	0.35	0.006	--	0.014
D	4.80	--	5.30	0.189	--	0.209
D2	3.61	--	4.35	0.142	--	0.171
E	5.90	--	6.35	0.232	--	0.250
E2	5.42	--	5.90	0.213	--	0.232
E3	3.23	--	3.90	0.127	--	0.154
E4	3.69	--	4.55	0.145	--	0.179
L	0.61	--	1.80	0.024	--	0.071
L2	0.05	--	0.36	0.002	--	0.014
e	--	1.27	--	--	0.050	--

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